

In the Claims:

1. (Currently Amended) An integrated circuit comprising:
a substrate;
a first insulating layer on the substrate that includes therein a first hole passing therethrough that includes a floor adjacent the substrate and a sidewall;
a first conductive contact that extends conformally on the sidewall and floor to define a groove in the first hole;
a second insulating layer on the first insulating layer remote from the substrate that includes therein a second hole passing therethrough that exposes the groove; and
a second conductive contact in the second hole and in the groove;
wherein the first conductive contact comprises a first barrier layer on the sidewall and floor and a first conductive layer on the first barrier layer remote from the sidewall and floor and wherein the second conductive contact comprises a second barrier layer on the first conductive layer and a second conductive layer on the second barrier layer remote from the first conductive layer; [[and]]
wherein the first barrier layer and the first conductive layer also extend onto the first insulating layer outside the first hole;
wherein the first insulating layer includes a third hole and a fourth hole passing therethrough; and
wherein the second insulating layer includes a fifth hole passing therethrough that exposes the fourth hole;
the integrated circuit further comprising:
a third conductive contact in the third hole;
a fourth conductive contact in the fourth and fifth holes; and
a third insulating layer on the second insulating layer remote from the first insulating layer that includes therein a sixth hole that exposes the second hole;
wherein the second conductive contact further extends into the sixth hole; and
wherein the second conductive contact also extends onto the third insulating layer outside the sixth hole.

2. (Original) An integrated circuit according to Claim 1 wherein the floor is directly on the substrate.

3. (Original) An integrated circuit according to Claim 1 wherein the second conductive contact fills the second hole and the groove.

4. (Canceled)

5. (Previously Presented) An integrated circuit according to Claim 1 wherein the first and second barrier layers comprise titanium and/or titanium nitride and wherein the first and second conductive layers comprise tungsten.

6. (Canceled)

7. (Original) An integrated circuit according to Claim 1 wherein the second conductive contact also extends onto the second insulating layer outside the second hole.

8-9. (Canceled)

10. (Currently Amended) An integrated circuit according to Claim [[8]] 1 further comprising:

a capacitor on the second insulating layer that is electrically connected to the fourth conductive contact.

11. (Canceled)

12. (Currently Amended) An integrated circuit according to Claim [[8]] 1 wherein the first hole is at least twice as wide as the third hole.

13-30. (Canceled)